## Claims

1. A plasma processing device comprising:

an inject plate;

an upper electrode; and

a hybrid ball-lock device removably securing the inject plate to the upper electrode.

- 2. The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises an actuating hybrid ball-lock device.
- 3. The plasma processing device of claim 1, wherein the hybrid ball lock device comprises an actuating hybrid spring-plunger device.
- 4. The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a ceramic head.
- 5. The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a silicon head.
- 6. The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a quartz head.
- 7. The plasma processing device of claim 1 wherein the hybrid ball-lock devices comprises an anodized aluminum head.
- 8. The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a metallic head.
- 9. The plasma processing device of claim 6 wherein the head is coated with a ceramic material.
- 10. The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises a CRES fastener housing.

- 11. The plasma processing device of claim 1 wherein the hybrid ball-lock device or threaded shaft is removably connected to a release button.
- 12. The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises at least one retaining ball.
- 13. A method of using a hybrid ball-lock device in a plasma processing device comprising the steps of:

communicatively locating a first surface of a first plasma processing device component adjacent a second surface of a second plasma processing device component;

inserting a hybrid ball-lock device into a recess located in at least one of the first and second plasma processing device components;

wherein the hybrid ball-lock device is inserted until a retaining ball is in communication with a retaining ball receiving recess contained within at least one of the first and second plasma processing device components.

- 14. The method of using a hybrid ball-lock device as claimed in claim 13, wherein the ball-lock device comprises a hybrid spring plunger type ball-lock device.
- 15. The method of using a hybrid ball-lock device as claimed in claim 13, wherein the hybrid ball-lock device comprises an actuating type hybrid ball-lock device.
- 16. The method of using a hybrid ball-lock device as claimed in claim 13, wherein at least a second hybrid ball-lock device is used.
- 17. The method of using a hybrid ball lock device as claimed in claim 13, wherein the first plasma processing device component comprises an upper electrode including an upper electrode portion and a lower electrode portion, and the head of the hybrid ball-lock device is in contact with an inject plate.

18. The method of using a hybrid ball-lock device as claimed in claim 17, further comprising interposing a baffle plate and a lower electrode between the upper electrode portion and the inject plate, wherein the baffle plate and the lower electrode portion includes holes therein for receiving the hybrid ball-lock device.